

PRINTED CIRCUIT BOARD MANUFACTURING METHOD

Abstract

A method of manufacturing a printed circuit board is disclosed. A seed layer is removed while etching of a circuit pattern is prevented. In a printed circuit board manufacturing process according to a semi-additive method, a seed layer is formed by electroless copper plating. Using a resist pattern, a circuit pattern is formed by electrolytic copper plating. After the formation of the circuit pattern, the exposed regions of seed layer are subjected to etching. According to the invention, an etching liquid at a temperature of about 15°C or less is used. As a temperature of the etching liquid is lowered, a potential difference between the seed layer and the circuit pattern increases. Due to the increase in potential difference, the seed layer becomes more susceptible to being etched, while the circuit pattern becomes less susceptible to being etched.